

PROTECTION PRODUCTS

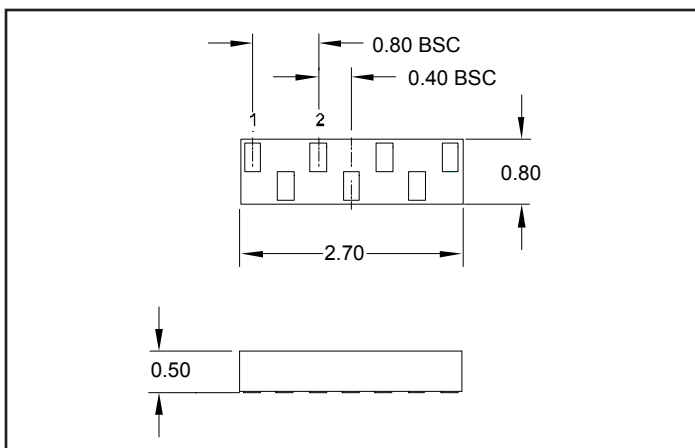
Description

The RClamp®3346P provides ESD protection for high-speed data interfaces. It features a high maximum ESD withstand voltage of $\pm 17\text{kV}$ contact and $\pm 20\text{kV}$ air discharge per IEC 61000-4-2. RClamp3346P is designed to minimize both the ESD peak clamping and the TLP clamping. Package inductance is reduced at each pin resulting in lower peak ESD clamping voltage. The dynamic resistance is among the industry's lowest at 0.15 Ohms (typical). Maximum capacitance on each line to ground is 0.65pF allowing the RClamp3346P to be used in applications operating in excess of 5GHz without signal attenuation. Each device will protect up to six lines (three high-speed pairs).

The RClamp3346P is in a 7-pin SGP2708N7 package measuring 2.7 x 0.8mm with a nominal height of 0.50mm. The leads have a nominal pin-to-pin pitch of 0.40mm. Flow-through package design simplifies PCB layout and maintains signal integrity on high-speed lines.

The combination of low peak ESD clamping, low dynamic resistance, and innovative package design enables this device to provide the highest level of ESD protection for applications such as USB 3.0, eSATA, and DisplayPort.

Package Dimension



Features

- ESD protection for high-speed data lines to
 - ♦ IEC 61000-4-2 (ESD) $\pm 17\text{kV}$ (Contact), $\pm 20\text{kV}$ (Air)
 - ♦ IEC 61000-4-5 (Lightning) 5A (8/20 μs)
 - ♦ IEC 61000-4-4 (EFT) 40A (5/50ns)
- Package design optimized for high speed lines
- Flow-Through design
- Protects six high-speed lines
- Low capacitance: 0.65pF Maximum (I/O to Ground)
- Low ESD clamping voltage
- Low dynamic resistance: 0.15 Ohms (Typical)
- Solid-state silicon-avalanche technology

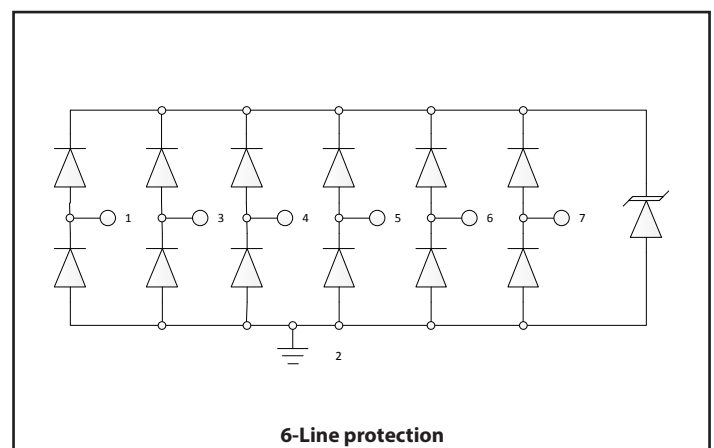
Mechanical Characteristics

- SGP2708N7 7-pin package (2.7 x 0.8 x 0.50mm)
- Pb-Free, Halogen Free, RoHS/WEEE compliant
- Lead Pitch: 0.4mm (intra-pair)
- Lead Finish: NiPdAu
- Marking: Marking code
- Packaging: Tape and Reel

Applications

- USB 3.0
- eSATA
- Display Port
- LVDS

Schematic & Pin Configuration



Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	4.5	A
ESD per IEC 61000-4-2 (Air) ⁽¹⁾ ESD per IEC 61000-4-2 (Contact) ⁽¹⁾	V_{ESD}	± 20 ± 17	kV
Operating Temperature	T_J	-40 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

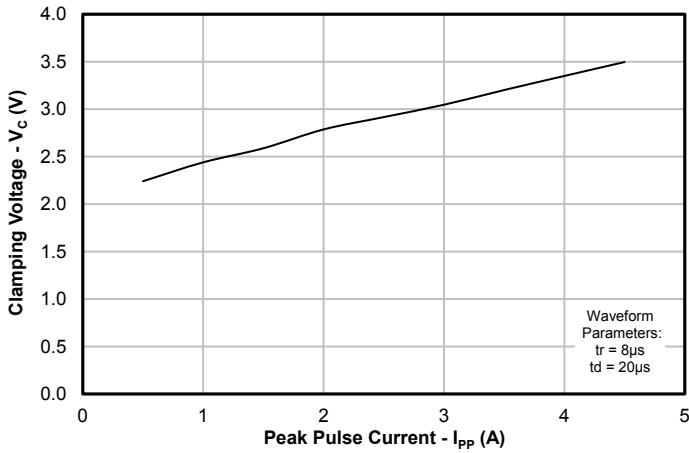
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}	Any I/O to GND			3.3	V
Reverse Breakdown Voltage	V_{BR}	$I_{BR} = 10\mu A$	7	8	9	V
Reverse Leakage Current	I_R	$V_{RWM} = 3.3V$ Any I/O to GND	$T = 25^\circ C$	0.01	0.05	μA
			$T = 125^\circ C$		0.150	
Clamping Voltage	V_C	$t_p = 8/20\mu s$ Any I/O to GND	$I_{PP} = 1A$	2.5	3.5	V
			$I_{PP} = 4.5A$	3.5	4.5	
ESD Clamping Voltage ²	V_C	$t_p = 0.2/100ns$	$I_{PP} = 16A$	5.5		V
			$I_{PP} = -16A$	-3		
Dynamic Resistance (positive) ^{2,3}	R_{DYN}	$t_p = 0.2/100ns$		0.15		Ω
Dynamic Resistance (negative) ^{2,3}	R_{DYN}	$t_p = 0.2/100ns$		0.14		
Junction Capacitance	C_J	$V_R = 0V, f = 1MHz, \text{Any I/O to GND}$		0.60	0.65	pF
		$V_R = 0V, f = 1MHz, \text{Between I/O pins}$		0.30	0.40	

Notes

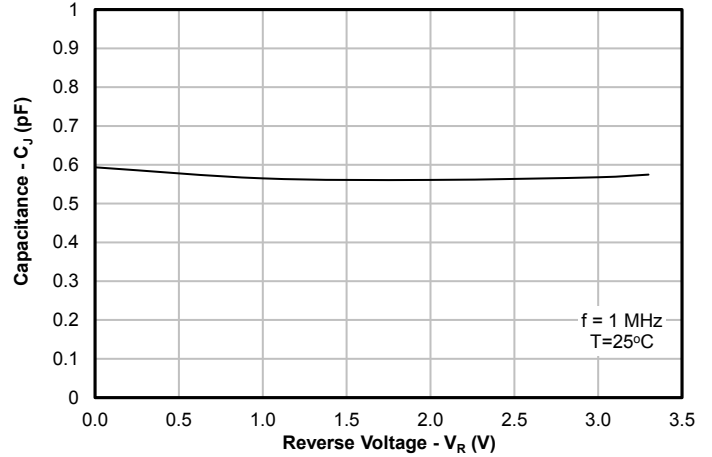
- 1) Measured with a 20dB attenuator, 50 Ohm scope input impedance, 2GHz bandwidth. ESD gun return path connected to ESD ground plane.
- 2) Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.
- 3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

Typical Characteristics

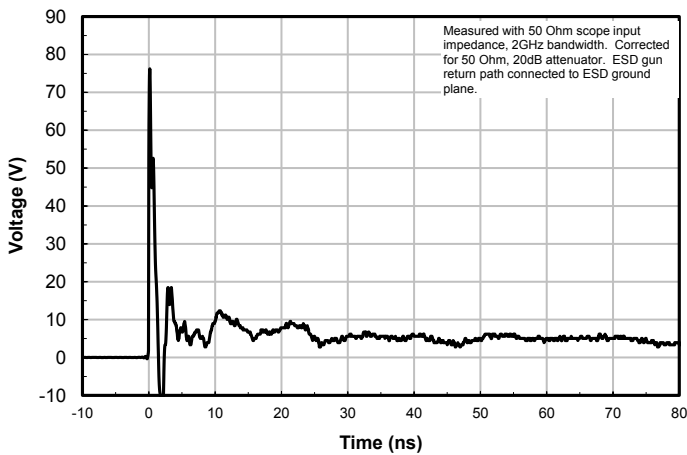
**Clamping Voltage vs. Peak Pulse Current
(Between any I/O and Ground)**



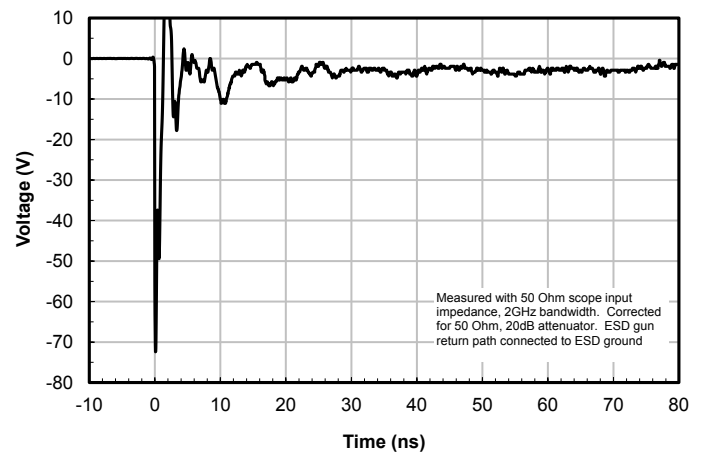
**Junction Capacitance vs. Reverse Voltage
(Between any I/O and Ground)**



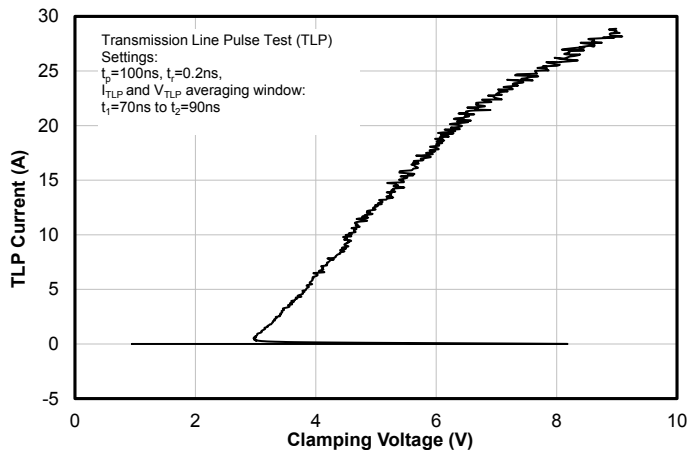
**ESD Clamping (+8kV Contact per IEC 61000-4-2)
(Between any I/O and Ground)**



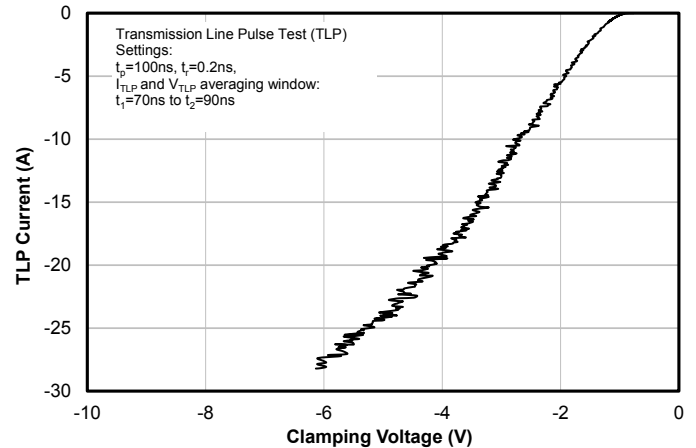
**ESD Clamping (-8kV Contact per IEC 61000-4-2)
(Between any I/O and Ground)**



TLP Characteristic (Positive)

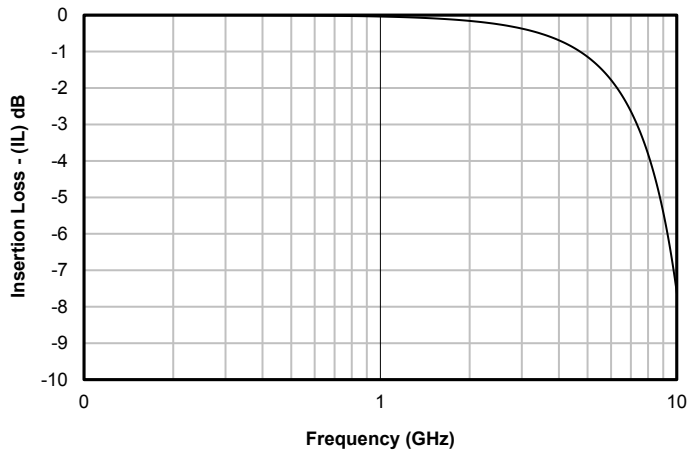


TLP Characteristic (Negative)

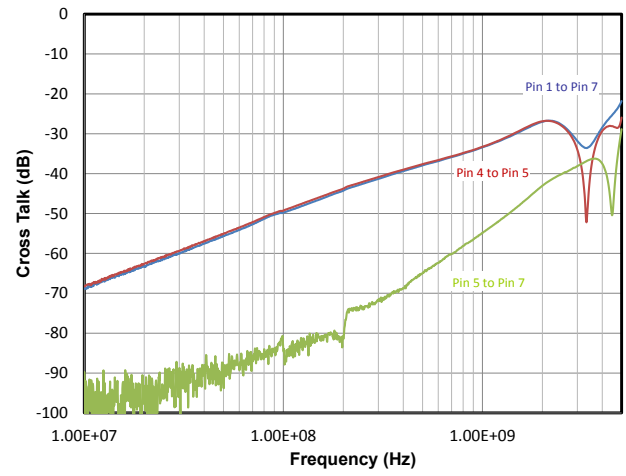


Typical Characteristics (Continued)

Insertion Loss - S21



Analog Crosstalk



Application Information

Protecting USB 3.0 Ports

RClamp3346P is designed to protect all six USB 3.0 SuperSpeed and high speed differential lines. PCB traces enter and exit each I/O pin and ground is connected at pin 2. For best results, it is recommended that the ground connection be made using a filled via-in-pad. The via should be filled with a conductive paste. This technique saves board space and reduces parasitic inductance in the ground path. Figures 2 and 3 are examples of how to route high speed differential traces through the RClamp3346P. Differential impedance of each pair can easily be controlled for USB 3.0 (85 Ohms +/- 15%).

The RClamp3346P should be placed as close to the connector as possible for optimum ESD performance. Internal construction of the RClamp3346P has been optimized to minimize series inductance within the package. This helps to reduce the ESD peak clamping voltage. Dynamic resistance is extremely low (typically 0.15 Ohms) further reducing the ESD clamping voltage.

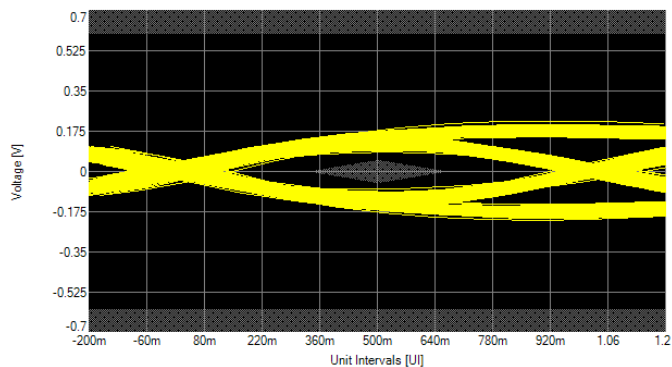


Figure 1 - USB 3.0 Eye Diagram with RClamp3346P

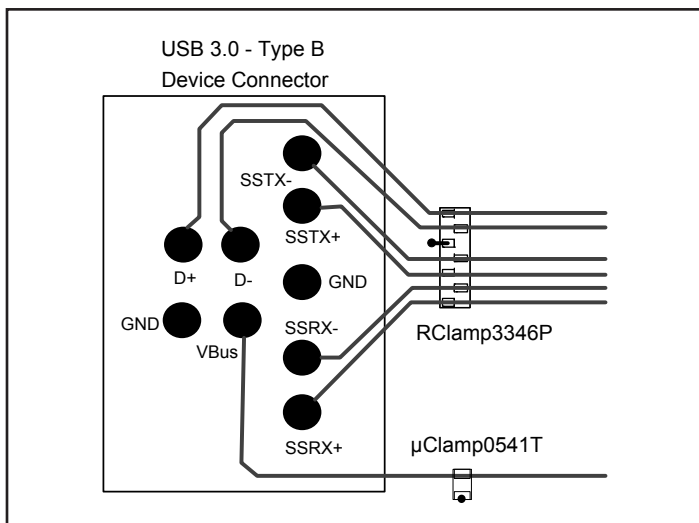


Figure 2 - Example USB 3.0 Layout (Type B Device Connector)

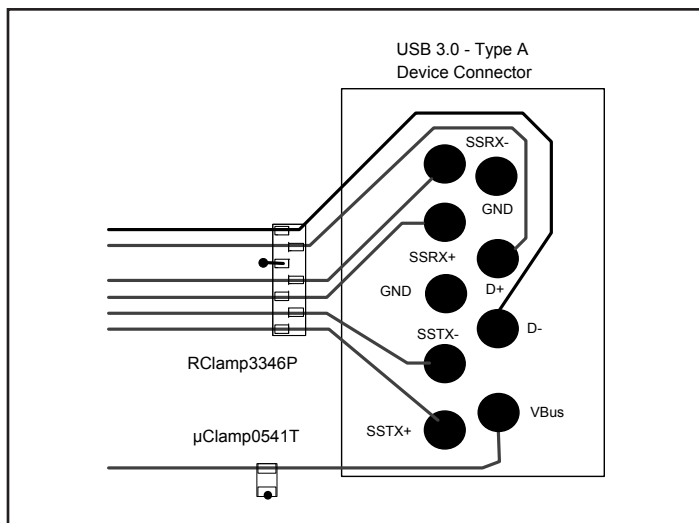


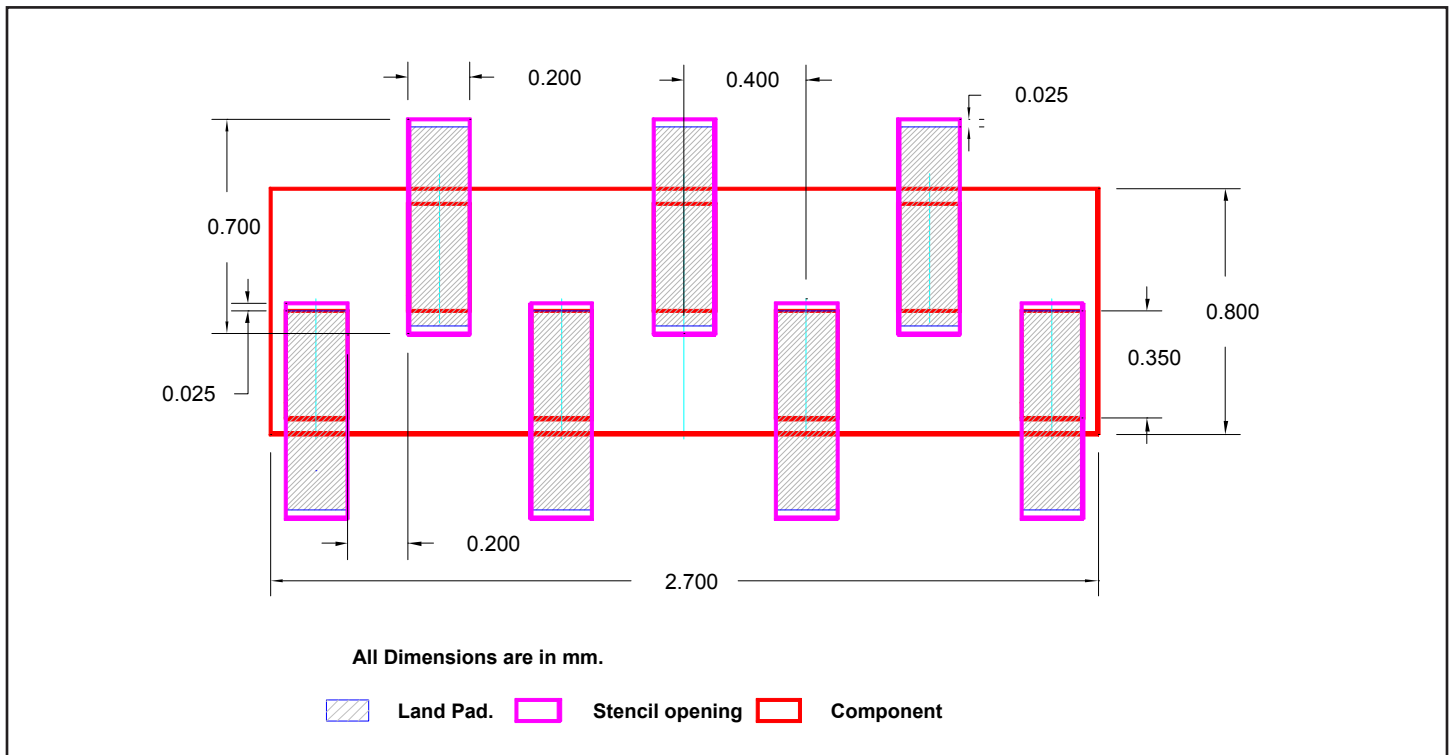
Figure 3 - Example USB 3.0 Layout (Type A Device Connector)

Application Information

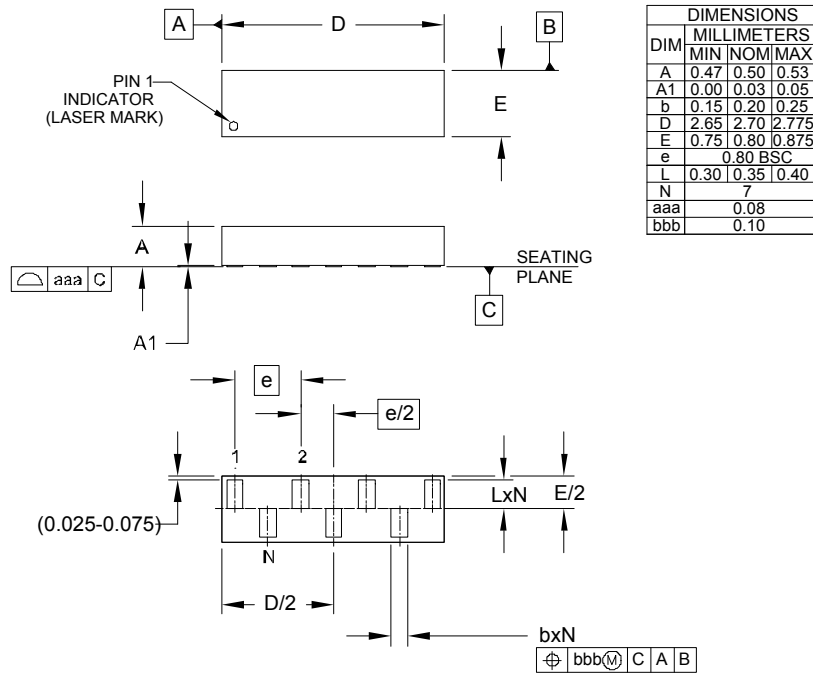
Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. Semtech's recommended assembly guidelines for mounting this device are shown in the Table 1. Figure 4 details Semtech's recommended aperture. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing parameters will require some experimentation to get the desired solder application.

Assembly Parameter	Recommendation
Solder Stencil Design	Laser cut, Electro-Polished
Aperture shape	Rectangular with rounded corners
Solder Stencil Thickness	0.100 mm (0.004")
Solder Paste Type	Type 4 size sphere or smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Non-Solder mask defined
PCB Pad Finish	OSP OR NiAu



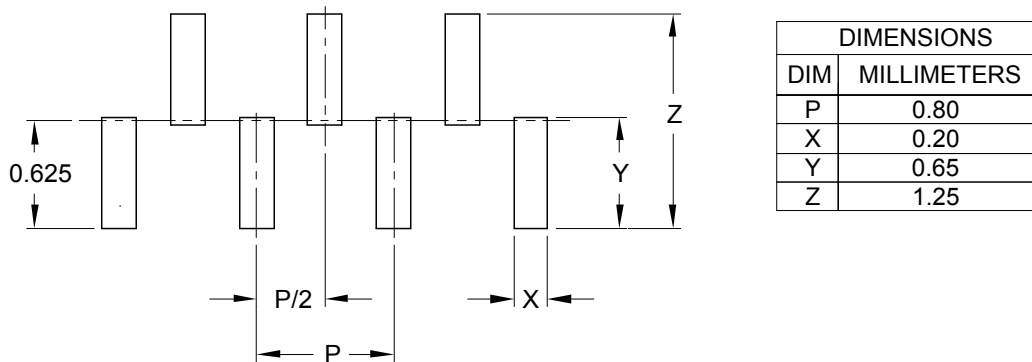
Outline Drawing - SGP2708N7



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

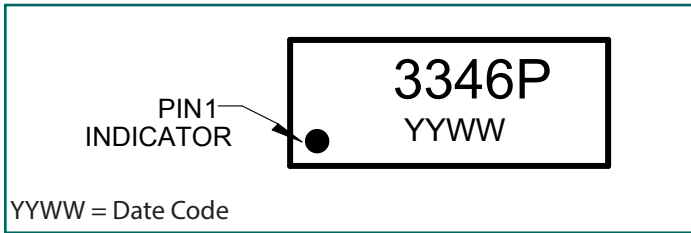
Land Pattern - SGP2708N7



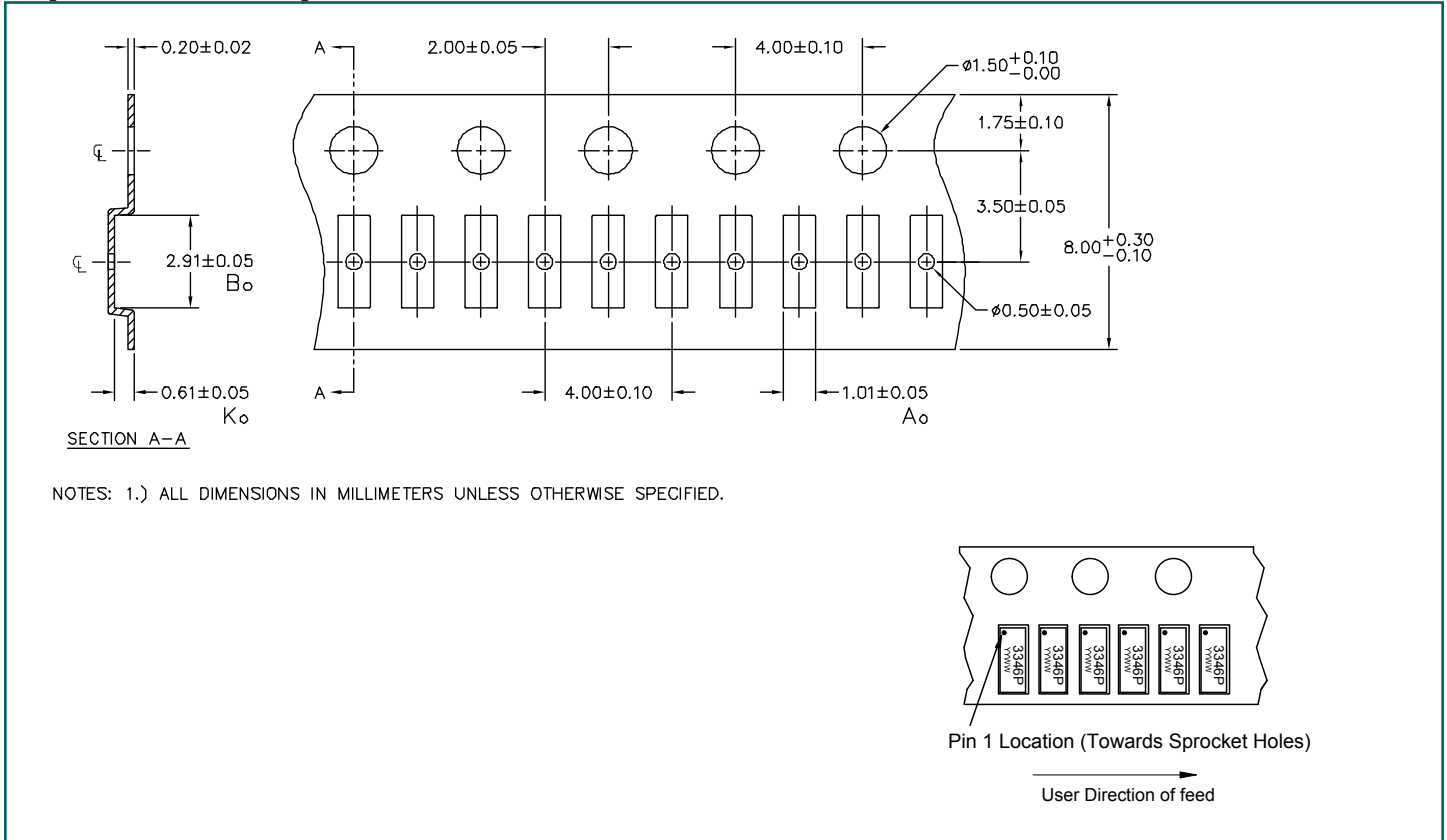
NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

Marking Code



Tape and Reel Specification



Ordering Information

Part Number	Qty per Reel	Reel Size
RClamp3346P.TNT	10,000	7"



IMPORTANT NOTICE

Information relating to this product and the application or design described herein is believed to be reliable, however such information is provided as a guide only and Semtech assumes no liability for any errors in this document, or for the application or design described herein. Semtech reserves the right to make changes to the product or this document at any time without notice. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. Semtech warrants performance of its products to the specifications applicable at the time of sale, and all sales are made in accordance with Semtech's standard terms and conditions of sale.

SEMTECH PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS, OR IN NUCLEAR APPLICATIONS IN WHICH THE FAILURE COULD BE REASONABLY EXPECTED TO RESULT IN PERSONAL INJURY, LOSS OF LIFE OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. INCLUSION OF SEMTECH PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE UNDERTAKEN SOLELY AT THE CUSTOMER'S OWN RISK. Should a customer purchase or use Semtech products for any such unauthorized application, the customer shall indemnify and hold Semtech and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs damages and attorney fees which could arise.

The Semtech name and logo are registered trademarks of the Semtech Corporation. All other trademarks and trade names mentioned may be marks and names of Semtech or their respective companies. Semtech reserves the right to make changes to, or discontinue any products described in this document without further notice. Semtech makes no warranty, representation or guarantee, express or implied, regarding the suitability of its products for any particular purpose. All rights reserved.

© Semtech 2015

Contact Information

Semtech Corporation
200 Flynn Road, Camarillo, CA 93012
Phone: (805) 498-2111, Fax: (805) 498-3804
www.semtech.com

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Semtech:](#)

[RCLAMP3346P.TNT](#)